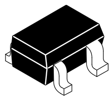
MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

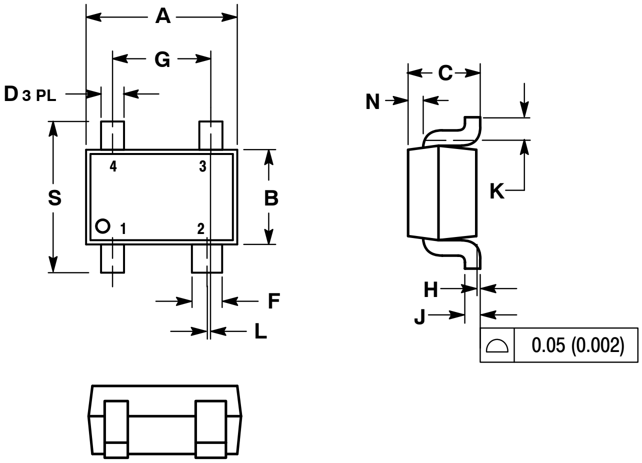
ON Semiconductor®



SC−82AB
CASE 419C−02
ISSUE F

DATE 22 JUN 2012

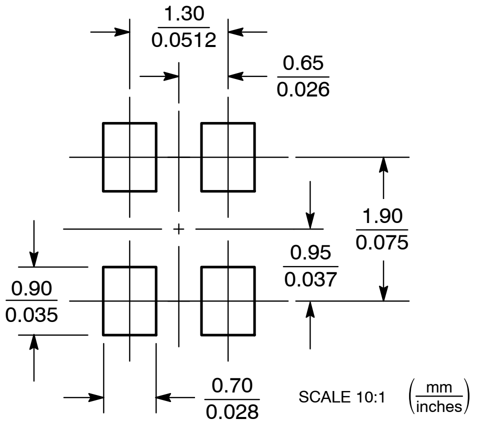
SCALE 4:1



NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. 419C−01 OBSOLETE. NEW STANDARD IS 419C−02.
4. DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

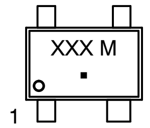
	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
A	1.80	2.20	0.071	0.087
B	1.15	1.35	0.045	0.053
C	0.80	1.10	0.031	0.043
D	0.20	0.40	0.008	0.016
F	0.30	0.50	0.012	0.020
G	1.10	1.50	0.043	0.059
H	0.00	0.10	0.000	0.004
J	0.10	0.26	0.004	0.010
K	0.10	---	0.004	---
L	0.05 BSC		0.002 BSC	
N	0.20 REF		0.008 REF	
S	1.80	2.40	0.07	0.09

SOLDERING FOOTPRINT*



*For additional information on our Pb−Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

GENERIC MARKING DIAGRAM*



XXX = Specific Device Code
M = Month Code
▪ = Pb−Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, “G” or microdot “ ▪”, may or may not be present.

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STATUS:	**ON SEMICONDUCTOR STANDARD**	
NEW STANDARD:		
DESCRIPTION:	**SC−82AB**	**PAGE 1 OF 2**

ISSUE	REVISION	DATE
C	ADDED NOTE 4, REQ. BY S. RIGGS.	26 JUN 2003
D	ADDED FOOTPRINT INFORMATION & UPDATED MARKING. REQ. BY B. LOFTS.	28 APR 2005
E	CORRECTED DIMENSION IN SOLDERING FOOTPRINT. REQ. BY B. LOFTS.	25 JAN 2006
F	CORRECTED DIMENSION N LABELS ON END VIEW. REQ. BY B. MARQUIS.	22 JUN 2012

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